

ULTRAFINE SOLDER POWDERS

# 超微焊粉

国际领先水平的超微锡基合金焊粉生产线



纯度高



粒度分布集中



球形度好



质量稳定

Fitech has the internationally leading level of ultrafine tin-based alloy solder powders production line, the product have the characteristics of high purity, good sphericity, concentrated grain size distribution and stable quality.

## T6

## T7



MIRA3 TESCAN 10µm Date: 01/15/2015

SEM HV: 15.0 KV SEM MAG: 5.00 kx WD: 9.34mm View Field: 43.3 µm Det: SE



MIRA3 TESCAN 10µm Date: 01/15/2015

SEM HV: 15.0 KV SEM MAG: 4.00 kx WD: 9.34mm View Field: 54.2 µm Det: SE

粒度分布

Particle size distribution

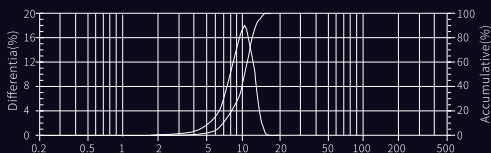
D10 µm	D50 µm	D90 µm	D99 µm	S.S.A Sq.m/c.c
6.35	9.42	12.12	14.01	0.69

粒度分布

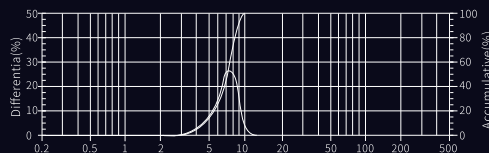
Particle size distribution

D10 µm	D50 µm	D90 µm	D99 µm	S.S.A Sq.m/c.c
4.04	6.05	7.82	9.08	1.09

粒径 (µm) (Diameter)



粒径 (µm) (Diameter)



# T8



# T9

### 粒度分布

### Particle size distribution

D10 μm	D50 μm	D90 μm	D99 μm	S.S.A Sq.m/c.c
3.57	5.27	6.76	7.80	1.24



MIRA3 TESCAN 2 μm Date: 01/15/2015

SEM HV: 15.0 KV SEM MAG: 15,00 kx WD: 9.14mm View Field: 14.4 μm Det: SE

### 粒度分布

### Particle size distribution

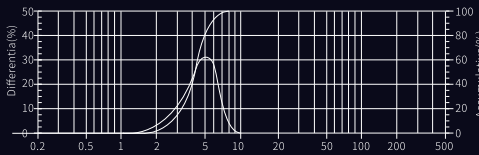
D10 μm	D50 μm	D90 μm	D99 μm	S.S.A Sq.m/c.c
2.36	3.34	4.17	4.74	1.93



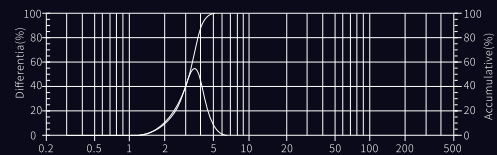
MIRA3 TESCAN 2 μm Date: 08/06/2014

SEM HV: 20.0 KV SEM MAG: 30.0 kx WD: 6.82mm View Field: 7.22 μm Det: SE

### 粒径 (μm) (Diameter)



### 粒径 (μm) (Diameter)



## Low Alpha

封装材料与半导体材料中的微量元素会释放出微量α射线，导致封装记忆体失忆（丢失数据）或导致中央处理器发生软错误（死机），要求封装材料做到α射线辐射量低于 Low Alpha 标准或低于 Ultra Low Alpha 标准：

**Low Alpha < 0.02 cph/cm<sup>2</sup>**

**Ultra Low Alpha < 0.002 cph/cm<sup>2</sup>**

Trace elements in package materials and semiconducting materials emit trace amounts of alpha rays, causing the package memory to fail (lost data) or causing the central processor to suffer soft errors (crash). The package material is required to achieve alpha ray radiation to a minimum of Low Alpha standard or lower than Ultra Low Alpha standard.

## 应用领域 Application

固晶、微凸点、窄间距、喷印、丝印、激光焊接等锡膏产品。应用在 Mini LED、Micro LED、SIP、FPC、微电子组装与半导体封装等领域。

Die attach solder paste, micro-bump narrow pitch solder paste, jet printing solder paste, laser soldering paste, are widely used in the field of microelectronic assembly and semiconductor packaging such as Mini LED, Micro LED, SIP, FPC.